



YOUSHANG SEMICONDUCTOR

**设计研发新型功率器件**

**各类小信号开关**

**中低压及高压大电流等场效应管**

0755-83047638

ysbdt@szyoushang.cn

www.szyoushang.cn



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## Description

This Bipolar Junction Transistor (BJT) is designed to meet the stringent requirements of Automotive Applications.

## Features

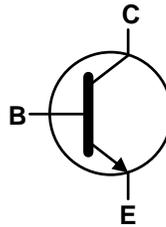
- $BV_{CEO} > 60V$
  - $I_C = 6A$  High Continuous Current
  - $I_{CM} = 12A$  Peak Pulse Current
  - Low Saturation Voltage  $V_{CE(SAT)} < 60mV @ 1A$
- Complementary PNP Type: NK-DSS60600MZ4

## Mechanical Data

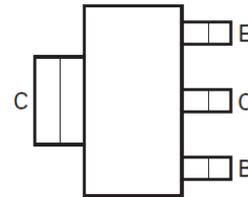
- Case: SOT223
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – Matte Tin Plated Leads. Solderable per MIL-STD-202, Method 208 <sup>Ⓔ</sup>
- Weight: 0.112 grams (Approximate)



Top View



Device Symbol



Top View  
Pin-Out

**Absolute Maximum Ratings** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	$V_{CB0}$	100	V
Collector-Emitter Voltage	$V_{CEO}$	60	V
Emitter-Base Voltage	$V_{EBO}$	6	V
Continuous Collector Current	$I_C$	6	A
Peak Pulse Collector Current	$I_{CM}$	12	A

**Thermal Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

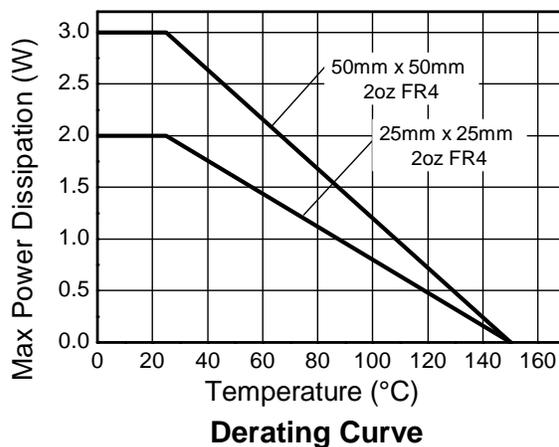
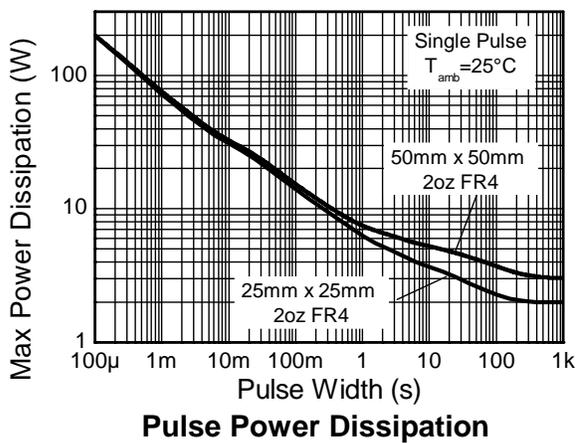
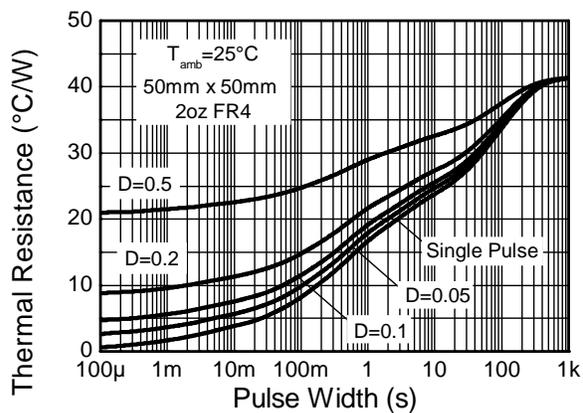
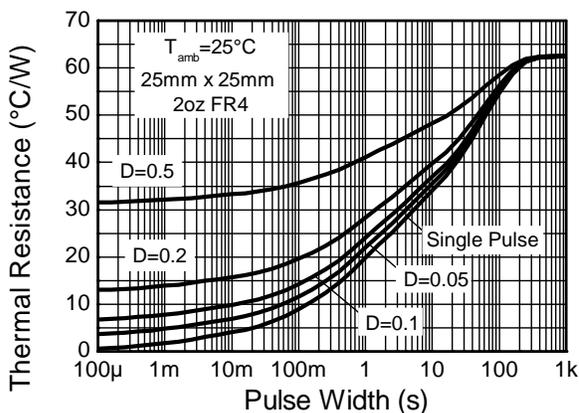
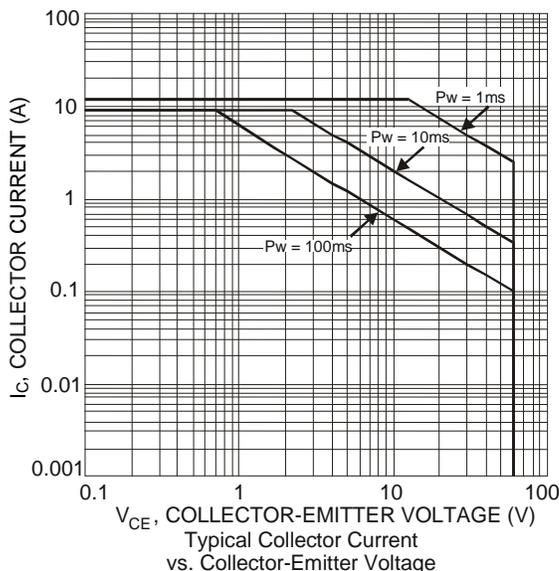
Characteristic	Symbol	Value	Unit
Power Dissipation	$P_D$	(Note 6) 3	W
		(Note 7) 2	
		(Note 8) 1.2	
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	(Note 6) 41.7	$^\circ\text{C/W}$
		(Note 7) 62.5	
		(Note 8) 104	
Thermal Resistance, Junction to Leads (Note 9)	$R_{\theta JL}$	12.9	$^\circ\text{C/W}$
Operating and Storage Temperature Range	$T_J, T_{STG}$	-55 to +150	$^\circ\text{C}$

**ESD Ratings** (Note 10)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

- Notes:
6. For a device mounted with the collector lead on 50mm x 50mm 2oz copper that is on a single-sided 1.6mm FR-4 PCB; device is measured under still air conditions whilst operating in steady-state.
  7. Same as note (6), except the device is mounted on 25mm x 25mm 2oz copper.
  8. Same as note (6), except the device is mounted on minimum recommended pad (MRP) layout.
  9. Thermal resistance from junction to solder-point (at the end of the collector lead).
  10. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

## Thermal Characteristics and Derating Information



**Electrical Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Conditions
<b>OFF CHARACTERISTICS</b>						
Collector-Base Breakdown Voltage	$BV_{CBO}$	100	—	—	V	$I_C = 100\mu\text{A}$
Collector-Emitter Breakdown Voltage (Note 11)	$BV_{CEO}$	60	—	—	V	$I_C = 10\text{mA}$
Emitter-Base Breakdown Voltage	$BV_{EBO}$	6	—	—	V	$I_E = 100\mu\text{A}$
Collector-Base Cutoff Current	$I_{CBO}$	—	—	100	nA	$V_{CB} = 40\text{V}, I_E = 0$
		—	—	50	$\mu\text{A}$	$V_{CB} = 40\text{V}, I_E = 0, T_J = +150^\circ\text{C}$
Emitter-Base Cutoff Current	$I_{EBO}$	—	—	100	nA	$V_{EB} = 6\text{V}, I_C = 0$
<b>ON CHARACTERISTICS (Note 11)</b>						
DC Current Gain	$h_{FE}$	150	—	—	—	$V_{CE} = 2\text{V}, I_C = 0.5\text{A}$
		120	—	360		$V_{CE} = 2\text{V}, I_C = 1\text{A}$
		100	—	—		$V_{CE} = 2\text{V}, I_C = 2\text{A}$
		50	—	—		$V_{CE} = 2\text{V}, I_C = 6\text{A}$
Collector-Emitter Saturation Voltage	$V_{CE(SAT)}$	—	—	40	mV	$I_C = 0.1\text{A}, I_B = 2.0\text{mA}$
		—	—	60		$I_C = 1\text{A}, I_B = 100\text{mA}$
		—	80	100		$I_C = 2\text{A}, I_B = 200\text{mA}$
		—	—	220		$I_C = 3\text{A}, I_B = 60\text{mA}$
Equivalent On-Resistance	$R_{CE(SAT)}$	—	40	50	m $\Omega$	$I_E = 2\text{A}, I_B = 200\text{mA}$
Base-Emitter Saturation Voltage	$V_{BE(SAT)}$	—	—	0.9	V	$I_C = 1\text{A}, I_B = 100\text{mA}$
Base-Emitter Turn-on Voltage	$V_{BE(ON)}$	—	—	0.9	V	$V_{CE} = 2\text{V}, I_C = 1\text{A}$
<b>SMALL SIGNAL CHARACTERISTICS</b>						
Transition Frequency	$f_T$	100	—	—	MHz	$V_{CE} = 10\text{V}, I_C = 100\text{mA}, f = 100\text{MHz}$
Output Capacitance	$C_{obo}$	—	26	—	pF	$V_{CB} = 10\text{V}, f = 1\text{MHz}$
Input Capacitance	$C_{ibo}$	—	325	—	pF	$V_{EB} = 5\text{V}, f = 1\text{MHz}$
Turn-On Time	$t_{ON}$	—	87	—	ns	$V_{CC} = 30\text{V}, I_{CC} = 150\text{mA}, I_{B1} = -I_{B2} = 15\text{mA}$
Delay Time	$t_D$	—	41	—	ns	
Rise Time	$t_R$	—	46	—	ns	
Turn-Off Time	$t_{OFF}$	—	294	—	ns	
Storage Time	$t_S$	—	250	—	ns	
Fall Time	$t_F$	—	44	—	ns	

 Notes: 11. Measured under pulsed conditions. Pulse width  $\leq 300\mu\text{s}$ . Duty cycle  $\leq 2\%$ .

Typical Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

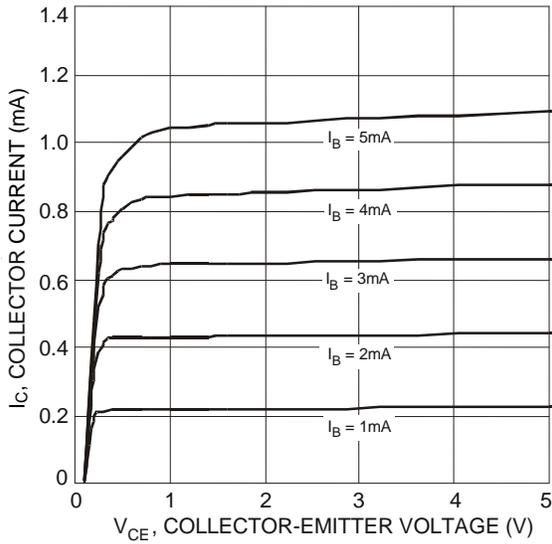


Fig. 1 Typical Collector Current vs. Collector-Emitter Voltage

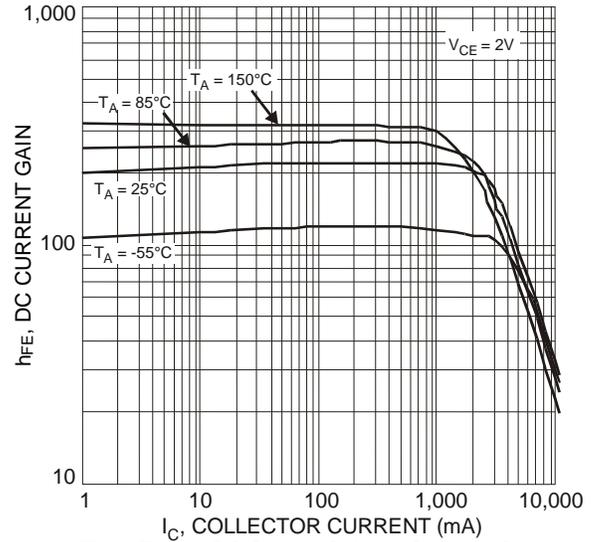


Fig. 2 Typical DC Current Gain vs. Collector Current

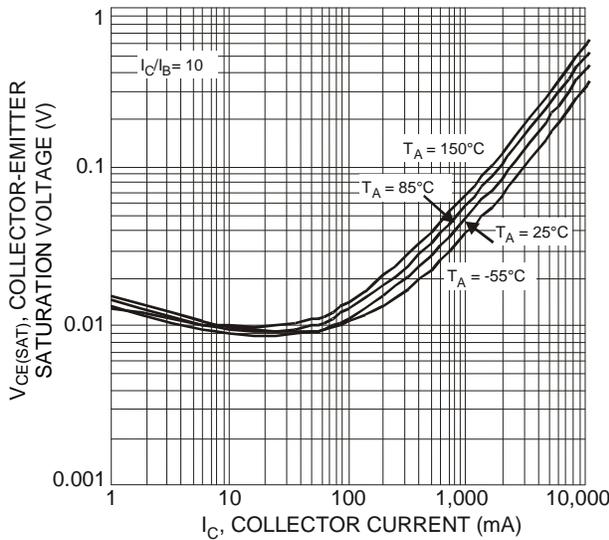


Fig. 3 Typical Collector-Emitter Saturation Voltage vs. Collector Current

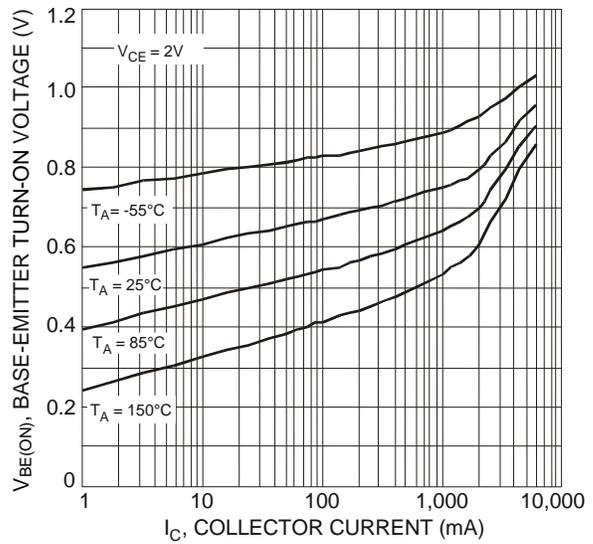


Fig. 4 Typical Base-Emitter Turn-On Voltage vs. Collector Current

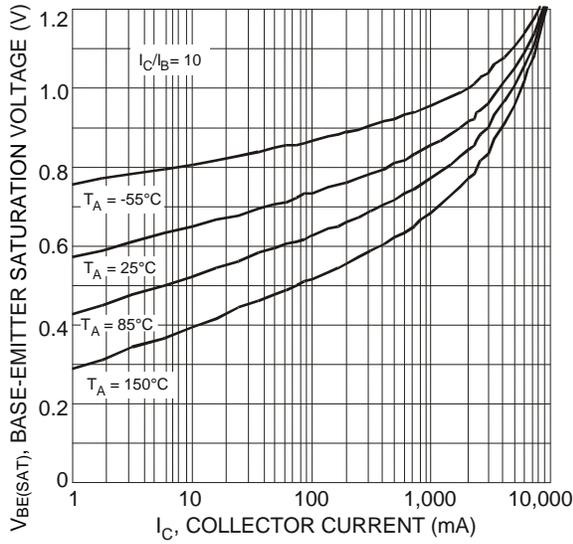


Fig. 5 Typical Base-Emitter Saturation Voltage vs. Collector Current

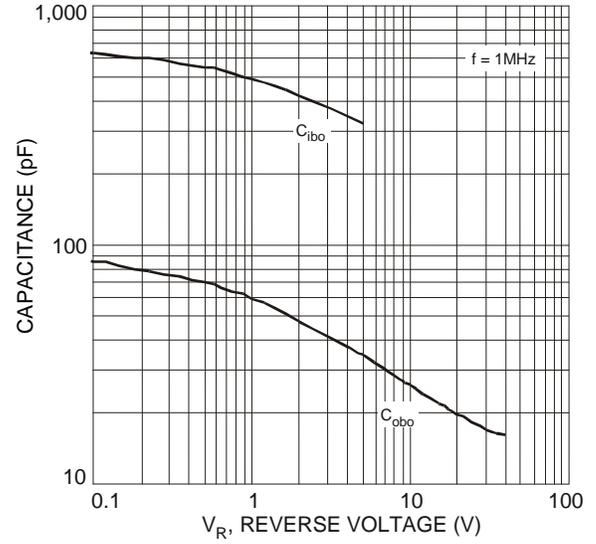


Fig. 6 Typical Capacitance Characteristics

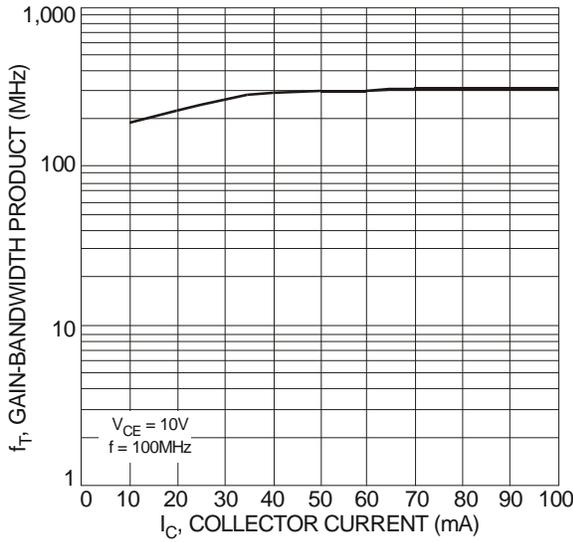
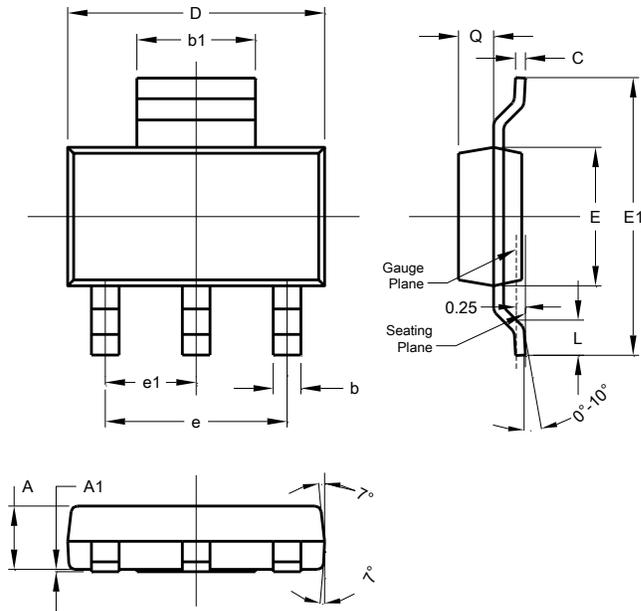


Fig. 7 Typical Gain-Bandwidth Product vs. Collector Current

Package Outline Dimensions

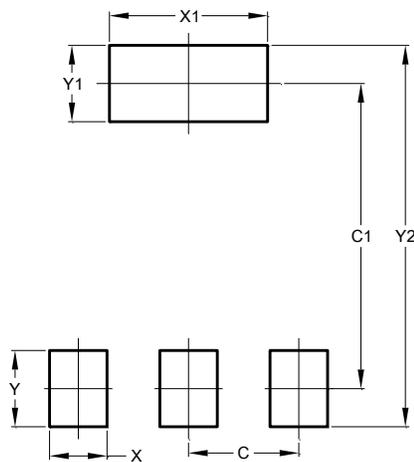
SOT223



SOT223			
Dim	Min	Max	Typ
A	1.55	1.65	1.60
A1	0.010	0.15	0.05
b	0.60	0.80	0.70
b1	2.90	3.10	3.00
C	0.20	0.30	0.25
D	6.45	6.55	6.50
E	3.45	3.55	3.50
E1	6.90	7.10	7.00
e	-	-	4.60
e1	-	-	2.30
L	0.85	1.05	0.95
Q	0.84	0.94	0.89
All Dimensions in mm			

Suggested Pad Layout

SOT223



Dimensions	Value (in mm)
C	2.30
C1	6.40
X	1.20
X1	3.30
Y	1.60
Y1	1.60
Y2	8.00